

# Preliminary Agenda 19 August 2009

– PRELIMINARY MEETING AGENDA –  
CE-2.0 COMMITTEE ON CONNECTOR AND SOCKET STANDARDS  
MEETING NO. 45

Doubletree Hotel  
411 West Bay Street  
Savannah, GA 31401

For reservations call: (912) 790-7000 or (800) 222-TREE

The CE-2.0 Committee on Connector Standards and its Subcommittees, Working Groups, and Special Task Groups will meet on 13 – 14 October (2 day meeting). The meeting will start at 9:00 AM on **Tuesday 13 October 2009** and conclude at 4:30 PM on **Wednesday 14 October 2009**.

**Note: The meeting will run sequentially, with no specific time scheduled for the individual agenda items shown below. The Chairman may vary the sequence as needed. Members are requested to plan on attending the meeting for a full two days (early departures effect the completion of agenda work).**

**If any SP receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting. It is the responsibility of the member to submit comments in writing prior to the meeting.**

**1. Approval of the 28 – 29 April 2009 minutes**

**2. CHAIRMAN’S REPORT AND ANNOUNCEMENTS (Frank Ruffino, Chairman)**

**3. SUBCOMMITTEE MEETINGS**

CE-2.1 Test Procedures (Chairman: Carl Fritz, Vice Chairman, Max Peel)

CE-2.3 Contact Specifications (was subcommittee CE-2.6) (Chairman: Dave Bouzek)

CE-2.4 Editing Subcommittee (was subcommittee CE-2.7) (Chairman: Carl Fritz)

CE-2.5 International Standards Subcommittee (was subcommittee CE-2.8) (Chairman: Jeff Toran)

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## 4. CONNECTOR AND SOCKET DETAIL SPECIFICATIONS

### 4.1. Specifications by Project Number

#### A. SP-4970, EIA-540DAAA-A, Detail, DIP

Sent second letter was sent to EIA to process the EDEC ballot on 6 October 2005.

This will be reissued as a new ballot.

#### B. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

Sent second letter was sent to EIA to process the EDEC ballot on 6 October 2005.

This will be reissued as a new ballot.

#### C. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

A second letter (mccwil269) was sent to Cecelia Yates (EIA Staff) EDEC ballot on 14 August 2006.

This will be reissued as a new ballot.

### 4.2 New Business

#### A. New Specification (Frank Ruffino)

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Frank Ruffino introduced a new connector detail specification for the "Mini-Change A-Size (2-6 pole)" connector.

The unanimously agreed to take this on as a project to create a new Detail Specification. Frank Ruffino has agreed to be project leader. It was moved by Kevin Rickard and seconded by Don Chambers to obtain a project number and send out on letter ballot or SP as determined by the project leader.

## B. Connector and Socket Specification Status

Carl Fritz gave a presentation on the status of all connector and socket specification that he extracted from the EIA database that appear to be the responsibility of CE-2.0. He will coordinate review of the accuracy with EIA. The following tables reflect his findings.

Connector Specifications Past Due for 5-Year Review					
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
7000000	A	Generic Specification for Electronic and Electrical Connectors of Certified Quality (for Frequencies Essentially Below 3 MHz)	August-96	July-01	7
270		Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification	January-62	December-66	42
280	C	Solderless Wrapped Electrical Connections	May-92	May-97	12
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet	June-70	May-75	34
380	A	Electrical Connectors, Small Contact Standard for	January-78	December-82	26
406		General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A	January-74	December-78	30
429		Connectors, Electrical Flat Cable Type-IPC FC-218B	January-76	December-80	28
616	A	Detail Specification for 2 Millimeter, Two-Part Connectors for Use with Printed Boards and Backplanes	November-02	November-07	1
622	A	Glossary of Electrical Connector Related Terms	August-07	August-12	-4
700A0AA		Detail Specification for 1.27 mm Pitch, Ribbon Contact, Trapezoidal Shaped, Shielded I/O Connector	April-96	April-01	8
700A0AD		Detail Specification for the Interface of the 1.27 mm Pitch, Ribbon Contact (Leaf Spring), Trapezoidal Shaped, Self-Locking I/O Connector	November-97	October-02	6
700A0AE		Detail Specification for Trapezoidal Connectors with Nonremovable Ribbon Cable Contacts on 1.27mm Pitch Double Row Used with Single Connector Attachments (SCA2)	January-00	December-04	4
700A0AF		Detail Specification for Trapezoidal Shielded Connector 0.8 mm Pitch Used with Very High Density Cable Interconnect (VHDCI)	July-00	June-05	4

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Connector Specifications Past Due for 5-Year Review					
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
700AAAB	A	Detail Specification for 1.0 mm, Two-Part Connectors for Use with Parallel Printed Boards	January-96	December-00	8
700B000		Sectional Specification for Rectangular/Trapezoidal Connectors of Certified Quality	May-99	May-04	5
700BA00		Blank Detail Specification for Rectangular/Trapezoidal Connectors of Certified Quality	September-98	September-03	5
700BAAD		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "A"	May-00	April-05	4
700BAAE		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "B"	May-00	April-05	4
700C000		Sectional Specification for Circular Multicontact Connectors of Assessed Quality (for Frequencies Essentially Below 3 MHz)	January-97	January-02	7
700D000		Sectional Specification for Discrete Contacts of Certified Quality (for Use in dc/Low Frequency Analog Applications and in Digital Applications Employing High Speed Data Rates)	January-98	January-03	6
710		Requirements Guide for Space Grade Electrical Connectors	October-97	October-02	6
IS-47		Contact Termination Finish Standard for Surface Mount Devices	July-87	June-92	17
IS-753		Two-Part High Density Blade and Backplane Tuning Fork Connector	February-98	February-03	6
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment	April-92	April-97	12

- Approved to be obsoleted or rescinded

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Socket Specifications Past Due for 5-Year Review					
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment	February-92	January-97	12
540B0AA	A	Detail Specification for Production Ball Grid Array (BGA) High Pin Count (1089 Pins and Greater) Socket for Use in Electronic Equipment-Revision	October-01	September-06	2
540BAAA	A	Detail Specification for Mechanically Actuated (Zero and Low Insertion Force) Sockets for Pin Grid Array Devices with 2.54 mm X 2.54 mm (0.1 in X 0.1 in) Spacing for Use in Electronic Equipment	August-96	August-01	7
540CAAC	A	Detail Specification for 2 Pole, 10 A Relay Sockets	November-98	November-03	5
540CAAD	A	Detail Specification for 2 Pole, 5 A Relay Sockets	August-99	August-04	4
540CAAE	A	Detail Specification for 3 Pole, 10 A Relay Sockets	August-99	August-04	4
540DB00		Blank Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets	June-93	December-97	11
540DB00		BLANK DETAIL SPEC FOR DIP SOCKETS W/DECOUPLING CAP	June-93	June-98	11
540DBAA		Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets for Use in Electronic Equipment	January-94	December-98	10
540E000		Sectional Specification for Round-Style Sockets for Use in Electronic Equipment	February-93	February-98	11
540FA00	A	Blank Detail Specification for Multi-Package Module Sockets for Use in Electronic Equipment	April-92	March-97	12
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540G000		Sectional Specification for Burn-In Sockets for Use in Electronic Equipment	January-93	December-97	11
540GA00		Blank Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11

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Socket Specifications Past Due for 5-Year Review					
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540HA00		Blank Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	May-00	April-05	4
540HAAA		Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	June-00	May-05	4
540J000		Sectional Specification for Battery Holders for Use in Electronic Equipment	May-00	April-05	4
540J0AA		Detail Specification for Cylindrical Battery Holders, Standard Profile, for Use in Electronic Equipment	May-00	April-05	4
540J0AB		Detail Specification for Coin Cell Battery Holders for Use in Electronic Equipment	June-01	May-06	3
674	A	Specification for Dimensions and Connectors Locations of Small Form Factor 45 millimeter (1.8 inch) Disk Drive	August-06	August-11	-3
675		Specification for Small Form Factor 33.0 mm (1.3 in) Disk Drives	January-96	December-00	8
676	A	Specification for Parallel 1.8 inch Drive Form Factor (78 millimeter x 54 millimeter)	June-06	June-11	-2
677		Specification for Small Form Factor Power Connector Pin Dimensions	June-97	June-02	7
740		Specification for Small Form Factor 88.9 mm (3.5 in) Disk Drives	July-99	June-04	5
741		Specification for Small Form Factor 133.35 mm (5.25 in) Disk Drives	May-01	April-06	3
773		Check List for Document Development and Revision	May-00	April-05	4
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5	May-71	April-76	33
IS-701		Production Ball Grid Array (BGA) Socket Test Specification	July-96	July-01	7

- Approved to be obsoleted or rescinded
- Duplicate listing

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Unknown Connector Documents						
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
51		EMISSION LIMITATION AM BROADCAST TRANSMISSION	September-88	August-93		Number unidentifiable
5810000		GENERIC SPEC RECTANGULAR CONNECTOR FOR FREQUENCIES BELOW 3 MHZ				Number unidentifiable
5880000		GEN SPEC PRINTED BD CONNECTORS OF ASSESSED QUALITY				Number unidentifiable
437-1		ADDENDUM NO. 1 TO EIA-437 BASIC SENSITIVE SWITCHES	September-78	August-83		Number unidentifiable
437-2			May-78	April-83		RESCINDED 9/25/89
437-3			September-78	August-83		RESCINDED 9/25/89
437-4			September-89	August-94		RESCINDED 9/25/89
437-5		20 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-6		15 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-7		10 AMP DOUBLE SENSITIVE SWITCHES	June-80	May-85		Number unidentifiable
437-8		8 AMP DOUBLE SENSITIVE SWITCHES	June-80	June-85		Number unidentifiable
64		INTERIM STD, 2MM TWO-PART CONN FOR PRINT WIRING BD	March-91	March-96		Number unidentifiable
700A000		SECT SPEC FOR PRINTED BOARD CONNECTORS ESSENTIALLY BELOW 3MHZ				No record that specification was ever issued
700A0AG		DT SP TRAPEZOIDAL PIN-AND-SOCKET CONN FIBER CHANNEL APPLICATIONS				No record that specification was ever issued
700AAAA		DT SP 1.27 mm PITCH RIBBON CONTACT TRAPEZOIDAL SHIELDED I/O CONNC				No record that specification was ever issued
700BAAA		CONNECTOR ELECT RECTANGULAR SCOOP-PROOF LOW FORCE SUBMINIATURE				No record that specification was ever issued
700BAAB		CONNECTORS, ELECTRICAL, RECTANGULAR, BLIND-MATE, SCOOP-PROOF				No record that specification was ever issued
700BAAC		DT SP BLIND-MATE, SCOOP PROOF EVA LOW EARTH ORBIT LEO CONNECTOR				No record that specification was ever issued
700D0AA		HIGH DENSITY TUNING FORK COMPONENTS				No record that specification was ever issued
700DA00		DISCRETE CONTACT BLANK DETAIL SPECIFICATION				No record that specification was ever issued

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Unknown Socket Documents						
EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
540B0AB		Low Pin Count BGA				Sent letter to EIA to cancel project on 13 May 2008
540D0AA		DET. SPEC - SOCKETS FOR DUAL...PACKAGES	January-90	January-95		No record that specification was ever issued
540F0AG		DETAIL SPEC-SMALL OUTLINE DIMM DUAL-IN-LINE MEMORY MODULE SOCKETS				No record that specification was ever issued
540FAAE		DT SP DUAL IN-LINE MEMORY (DIMM) SOCKETS 1.27 MM VERTICAL MOUNT				No record that specification was ever issued
540FAAF		DT SP 8-BYTE 168 POSITION DUAL IN-LINE MEMORY MODULE SOCKET 1.27				No record that specification was ever issued
540JAAA		DT SP BURN-IN SOCKETS USE W/BALL GRID ARRAY DEVICE USE IN ELEC EQ				No record that specification was ever issued

## C. Obsolete or rescind all Generic, Sectional and Blank Detail Specifications (Carl Fritz)

The unanimously agreed to obsolete all Generic, Sectional and Blank Details Specifications. Carl Fritz has agreed to be project leader. It was moved by Don Chambers and seconded by Frank Ruffino to obtain a project number and send out on SP ballot.

- SP-5193 EIA-7000000, EIA-700B000, EIA-700BA00, EIA-700C000, EIA-700D000, EIA-540DB00, EIA-540E000, EIA-540FA00, EIA-540G000, EIA-540GA00, EIA-540HA00 and EIA-540J000 “Electrical Connector and Socket Specifications” (Carl Fritz)

Sent cover memo (mccwil382 and PINS form to EIA requesting a project number on 25 June 2009.

Received project numbers 25 June 2009.

Sent letter (mccwil385) and prepared SP ballot to EIA to rescind on 23 July 2009.

Ballot issued 23 July 2009 with a ballot expiration date of 23 September 2009.

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## D. SFF Committee Project Activities (Frank Ruffino)

There has been a request received to prepare approximately 22 detail specifications on behalf of the SFF Committee. The committee unanimously agreed to take this on as a project to create new detail specifications. Frank Ruffino has agreed to be project leader. It was moved by Don Chambers and seconded by Kevin Rickard to obtain a project number and send out on letter ballot or SP as determined by the project leader.

- SP or PN-5190 EIA-964, Detail Specification for QSFP+ Copper and Optical Modules (formerly SFF-8436) (Frank Ruffino)
- SP or PN-5191 EIA-965, Detail Specification for Mini Multilane Shielded Integrated Connector (formerly SFF-8642) (Frank Ruffino)

Sent cover memo (mccwil381 and PINS form to EIA requesting a project number on 11 June 2009 on behalf of Frank Ruffino.

Received project numbers 11 June 2009.

## 5. LIASION REPORTS

- A. DSCC, including Army, USAF, Navy; except NAVAIR (Ralph Antonelli)
- B. NAVAIR (Dwight Tabit)
- C. SAE (Dave Bouzek)
- D. ASTM (Frank Ruffino)

## 6. OTHER BUSINESS

- A. Review of questionnaire for CE-2.0 (Frank Ruffino)

Activity has been tabled for the time being.

- B. Documentation Structure Strategy (Carl Fritz) (Retained for Historical Purposes)

Consensus of the committee is that there is no valid reason to continue to use the generic, sectional and blank details. These documents should be obsoleted at the next review cycle. This has now been actively introduced as a project under new business for connectors and sockets.

This has been addressed in clause 4.2.C of these minutes and is now an active project.

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## 7. NEW BUSINESS

### A. Scope (Frank Ruffino)

Review our CE-2.0 Committee Scope. I think it needs adjustments and this has not been done after we merged CE-3.0. Frank agreed to prepare a revised scope of the committee.

### B. Committee Process (Carl Fritz)

Also include a review of the "Official" Process for ballots and resolving negative ballots. I will ask Bob to give us presentation on what we should be doing.

Carl to provide Bob Willis with the sequence of events document as well as the draft of the revised Purple rejection card that were discussed at the meeting.

### C. WEB Database Review (Carl Fritz and Frank Ruffino)

Discussed updating the database with Bob Willis. Carl has agreed to provide Bob with a listing of all standards and specification that he is aware of that are the responsibility of the CE-2.0 committee for review. Bob to provide Frank with a copy of the database for suggestions on layout and content.

## 8. CONNECTOR AND SOCKET SPECIFICATIONS (F. Ruffino)

'SFF-8087 Mini Multilane Series Connector: Unshielded',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8087.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8088 Mini Multilane Series Connector: Shielded',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8088.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8482 Internal Serial Attachment Connector',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8482.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8431 SFP+',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8431.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8432 IPF (Improved Pluggable Formfactor)',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8432.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

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'SFF-8433 IPF (Improved Pluggable Formfactor) Cage',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8433.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8436 QSFP Copper and Optical Transceivers',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8436.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8484 4-Wide Internal Serial Attachment Connector',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8484.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8642 Mini Multilane Series: Shielded Integrated Connector',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8642.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8079 SFP Rate and Application Selection',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8079.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8089 SFP Rate and Application Codes',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8089.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8416 Measurement & Performance Requirements for HPEI Bulk Cable',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8416.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8460 HSS Backplane Design Guidelines',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8460.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8100 Suite of <2.5" Form Factor Specifications',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8100.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8200 Suite of 2.5" Form Factor Specifications',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8200.pdf>,  
a suitable candidate to become a Publicly Accepted  
Specification project by assigning it a number.

'SFF-8300 Suite of 3.5" Form Factor Specifications',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8300.pdf>,

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a suitable candidate to become a Publicly Accepted Specification project by assigning it a number.

'SFF-8500 Suite of 5.25" Form Factor Specifications',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8500.pdf>,  
a suitable candidate to become a Publicly Accepted Specification project by assigning it a number.

'SFF-8448 SAS Sideband Utilization',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8448.pdf>,  
a suitable candidate to become a Publicly Accepted Specification project by assigning it a number.

'SFF-8485 Serial GPIO (SGPIO) Bus',  
viewable at <ftp://ftp.seagate.com/sff/SFF-8485.pdf>,  
a suitable candidate to become a Publicly Accepted Specification project by assigning it a number.

## 9. FUTURE MEETINGS

Respectfully submitted,

Frank Ruffino, Chairman CE-2.0

Prepared by  
Carl Fritz, Secretary CE-2.0